

## A 1.3 $\mu$ W, 5pJ/cycle sub-threshold MSP430 processor in 90nm xLP FDSOI for energy-efficient IoT applications

Paper ID# P6 Abhishek Roy<sup>1</sup>, Peter J. Grossmann<sup>2</sup>, Steven A. Vitale<sup>2</sup>, Benton H. Calhoun<sup>1</sup>

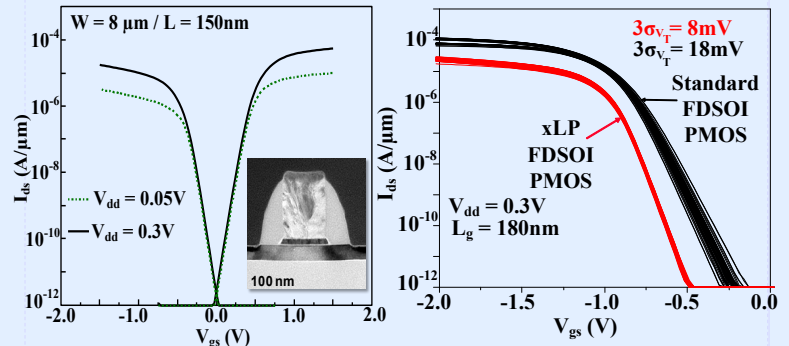
<sup>1</sup>University of Virginia, Charlottesville, VA USA <sup>2</sup>MIT Lincoln Laboratory, Lexington, MA USA

### 1. Introduction

This poster presents an implementation of a 16-bit MSP430 processor for ultra-low-power (ULP) systems catering to battery-less wireless sensor nodes, biomedical, and other IoT applications. Implemented in a custom extremely low power (xLP) 90nm FDSOI process, the processor

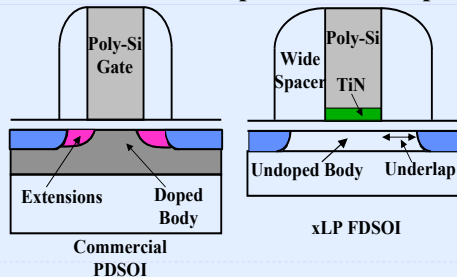
- Consumes 1.3 $\mu$ W operating at 0.4V while executing a QRS peak detection algorithm at 250 kHz.
- Supports the standard MSP430 instruction set architecture (ISA)
- The measured energy while operating at 250 kHz was 5pJ per cycle at 0.4V.
- The fabricated xLP devices show 55% reduction in threshold voltage ( $V_T$ ) variation compared to similar-sized transistors in a traditional FDSOI process.

### 4. Measured Results

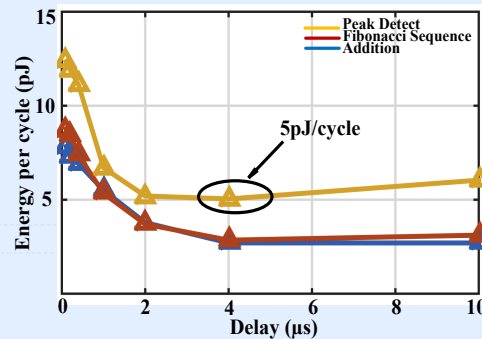


- 46 PMOS transistors characterized across two wafers
- $3\sigma$  variation in  $V_T$  was found to be 8mV

### 2. xLP FDSOI Device Description and Comparison

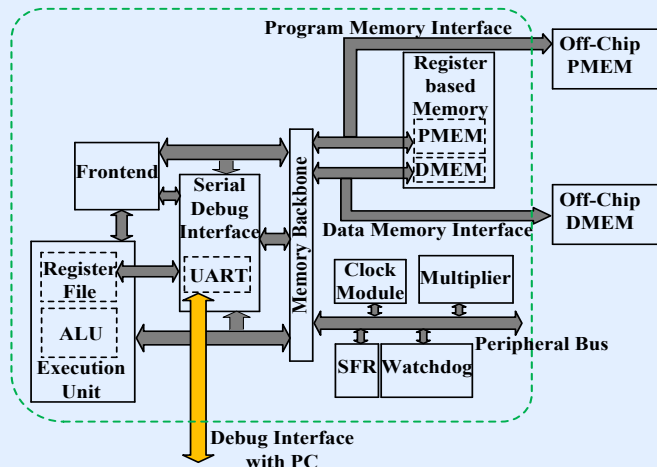


- xLP transistors are fabricated using 30-nm Si on 145-nm BOX
- The SiON gate dielectric thickness is 3.5nm, 5 metal layers of aluminum interconnect and SiO<sub>2</sub> dielectric
- Device engineering includes a 1020 °C, 5s rapid thermal anneal, ~10 nm of CoSi<sub>2</sub>, and a 20-min 400 °C hydrogen passivation anneal
- Eliminating channel doping reduces  $V_T$  variation caused by non-uniformity in SOI thickness and RDF
- $V_T$  is set by a work function-tuned TiN metal gate
- Device capacitances are minimized by 76% by eliminating source-drain extensions and employing wide nitride



- Min energy of 5pJ per cycle at 0.4V and 250 kHz running peak detection
- For higher performance, the processor can operate at 1MHz at 0.6V, consuming 6.7pJ per cycle
- By sacrificing 34% energy, 4x performance improvement can be achieved
- Measured minimum energy across 8 functional dies show a  $\sigma/\mu$  of 0.0405

### 3. MSP430 Processor Architecture



### 5. Comparison with prior work

	[1]	[2]	[4]	[11]	[12]	This Work
Technology	65nm	180nm	180nm	65nm	130nm	90nm FDSOI
Architecture	16-bit MSP430 compatible	ARM Cortex M0+	ARM Cortex M0	16-bit MSP430 compatible	16-bit MSP430 compatible	16-bit MSP430 compatible
Operating Voltage	0.3-0.6V	0.16-1.15V	0.6V	0.32-0.48V	0.55V-1.2V	0.38-0.9V
Min Energy	6-10pJ/cycle @ 0.5V	44.7pJ/inst@0.55V	17.2pJ/inst@0.26V	2.6pJ/cycle@0.375V executing FIR filtering	14.8pJ/cycle@0.6V	5pJ/cycle@0.4V executing peak detection
Operating Frequency	8.7kHz-1MHz	2Hz-15Hz	160-330kHz	25-71MHz	-	100kHz-10MHz
Area	1.62mm <sup>2</sup>	2.04mm <sup>2</sup> (CPU+U+MEM)	1.7mm <sup>2</sup> (CPU+MEM)	0.42mm <sup>2</sup>	5.13mm <sup>2</sup> (CPU+Mem+Accel)	0.44mm <sup>2</sup>